



# SCANNER MODULE SPECIFICATION

**CUSTOMER NAME:** MSI  
**CUSTOMER PRODUCT NAME:** FUTON+  
**BYD PRODUCT NAME:** EMC90800  
**BYD MODULE NAME:** BOCSAR0833-MIC9080

Customer Service Unit  
Division  
BYD COMPANY LIMITED

Rev 1.0

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## NOTICE

*This document is a general product description and maybe changed basing on customer's requirement.*





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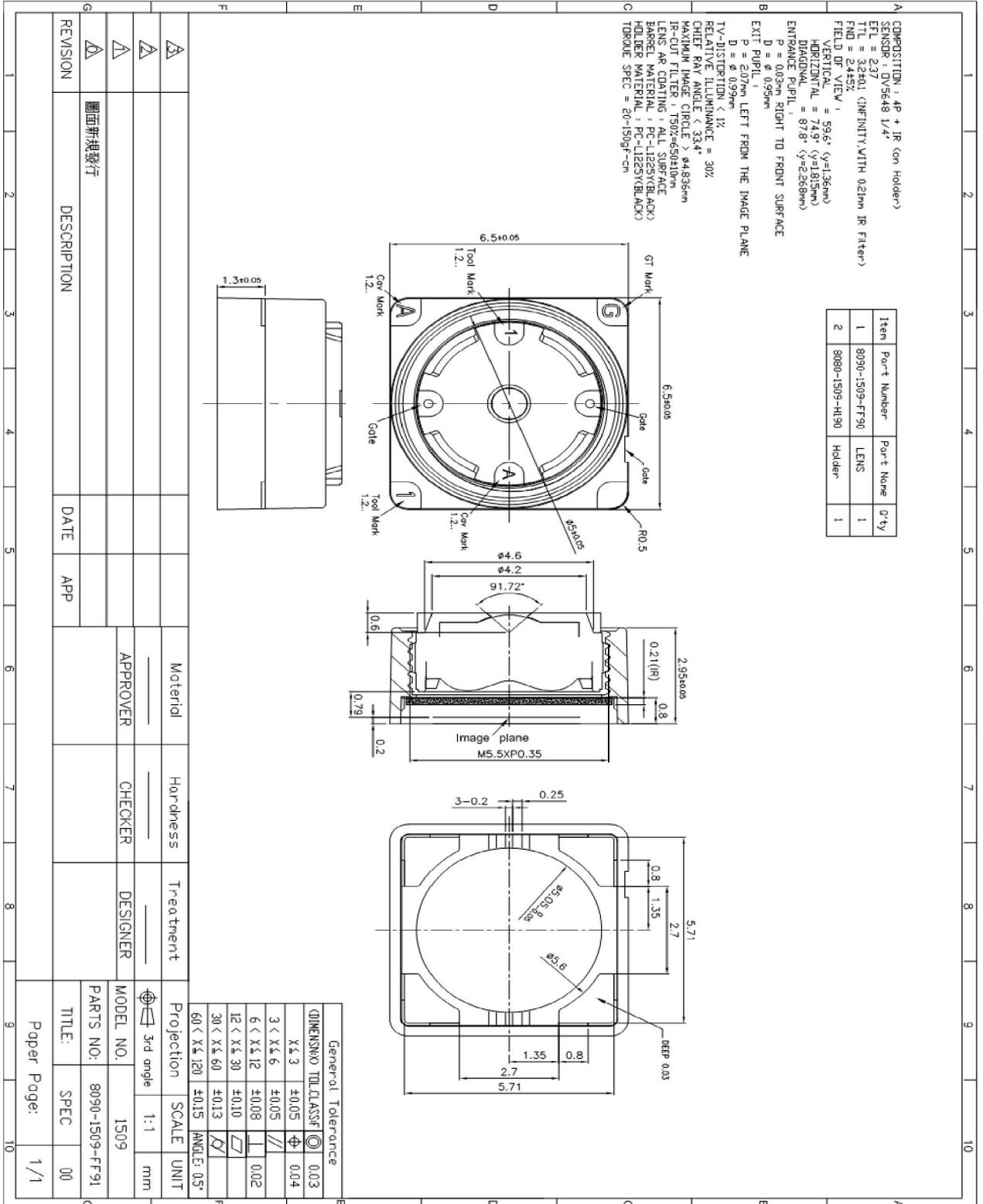
COMPOSITION : 4P + IR (on Holder)  
SENSOR : OV5648 1/4"  
EFL = 2.37  
TTL = 3.2±0.1 (INFINITY, WITH 0.21mm IR Filter)  
FNO = 2.4±5%  
FIELD OF VIEW :  
    VERTICAL = 59.6° (y=1.36mm)  
    HORIZONTAL = 74.9° (y=1.815mm)  
    DIAGONAL = 87.8° (y=2.268mm)  
ENTRANCE PUPIL :  
    P = 0.03mm RIGHT TO FRONT SURFACE  
    D = ∅ 0.95mm  
EXIT PUPIL :  
    P = 2.07mm LEFT FROM THE IMAGE PLANE  
    D = ∅ 0.99mm  
TV-DISTORTION < 1%  
RELATIVE ILLUMINANCE = 30%  
CHIEF RAY ANGLE < 33.4°  
MAXIMUM IMAGE CIRCLE > ∅4.836mm  
IR-CUT FILTER : T50%=650±10nm  
LENS AR COATING : ALL SURFACE  
BARREL MATERIAL : PC-L1225Y(BLACK)  
HOLDER MATERIAL : PC-L1225Y(BLACK)  
TORQUE SPEC = 20~150gf-cm

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BOCSAR0833-MIC9080 Scanner Engine Specification

Division  
Revision 1.0



Sensor Specification



## BOCSAR0833-MIC9080 Scanner Engine Specification

Division

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## Features

- 8Mp (4:3) still images at 30 fps
- 1.4 $\mu$  pixel with Aptina™ A-PixHS™ technology providing best-in-class low-light performance.
- Optional on-chip high-quality bayer scaler resizes 6Mp 30 fps HD video to 1080p30 (2Mp 30 fps).
- Serial MIPI interface supports either 4-lane, 3-lane, or 2-lane configurations and speeds up to 1Gbps/ lane.
- On-chip temperature sensor
- Support for external mechanical shutter
- Support for external LED or Xenon flash
- Programmable controls: gain, horizontal and vertical blanking, auto black level offset correction, frame size/rate, exposure, left-right and top-bottom image reversal, window size, and panning
- On-die phase-locked loop (PLL) oscillator
- Integrated position and color-based shading correction
- 8Kb one-time programmable memory (OTPM) for storing shading correction coefficients of three light sources and module information
- Internal VCM driver
- Slave mode for precise frame-rate control and for synchronizing two sensor

## Applications

- Mobile phones
- PC cameras

## Ordering Information

Table 1: Available Part Numbers

Part Number	Description
AR0833MBSC275MD20	Bare die

Table 2: Key Performance Parameters

Parameter	Typical Value
Array Format	3264 x 2448

## Features

Table 2: Key Performance Parameters

Parameter	Typical Value	
Primary modes	Full Resolution: 4:3 - 8Mp at 30 fps	
	16:9 - 6Mp at 30 fps	
	16:9 - 1080p HD at 30 fps	
Pixel size	1.4 $\mu$ m Back Side Illuminated (BSI)	
Optical format	1/3.2"	
Die size	6.86mm x 6.44mm (Area: 44.17mm <sup>2</sup> )	
Input Clock Frequency	6 - 27 MHz	
Interface	4-lane MIPI (2-lane and 3-lane modes supported); Max data rate: 1Gbps/lane	
Subsampling modes	X - Bin2, Sum2 Skip: 2x, 4x	
	Y - Sum2, Skip: 2x, 4x, 8x	
Output data depth	10 bits	
Analog gain	1x, 2x, 3x, 4x, 6x, 8x	
High Quality Bayer Scaler	Adjustable scaling up to 1/6x scaling	
Temperature sensor	10-bit, single instance on chip, controlled by two-wire serial I/F	
Compression	DPCM: 10-8-10, 10-6-10	
VCM AF driver	8-bit resolution	
3-D support	Frame rate and exposure synchronization	
Supply Voltage	Analog	2.5 - 3.1 V (2.8V nominal)
	Digital	1.14 - 1.3 V (1.2V nominal)
	Pixel	2.5 - 3.1 V (2.8V nominal)
	OTPM	1.7 - 1.9 V (1.8V nominal)
	I/O	1.7 - 1.9 V (1.8V nominal) or 2.5 - 3.1 V (2.8V nominal)
MIPI	1.14 - 1.3 V (1.2V nominal)	
Power consumption	400mW at 30 fps, 8Mp	
Responsivity	0.7V/lux-sec	
SNR <sub>MAX</sub>	36 dB	
Dynamic Range	65 dB	
Operating Temperature Range (at junction) -T <sub>j</sub>	-30°C to +70°C	

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**Table 5: Independent Power and Ground Domains**

Pad Name	Power Supply	Description
<b>Grounds</b>		
DGND (GNDPHY, GND_IO)	0V	Digital
VCM_GND	0V	VCM driver
AGND	0V	Analog
<b>Power</b>		
VAA	2.8V	Analog/VCM driver/OTPM
VAA_PIX	2.8V	Pixel/Analog
DVDD_1V2	1.2V	Digital
VDD_IO	1.8v/2.8V	IO
DVDD_1V2_PHY	1.2V	MIPI
DVDD_1V8	1.8V	OTPM

**Table 7: Power-down Sequence**

Definition	Symbol	Minimum	Typical	Maximum	Unit
EXTCLK to XSHUTDOWN	$t_0$	100	–	–	$\mu s$
XSHUTDOWN to supply 2.8V/1.8V	$t_1$	200	–	–	$\mu s$
Supply 2.8V/1.8V to supply 1.2V	$t_2$	0	200	–	$\mu s$
Supply 1.2V to VDD_IO	$t_3$	200	–	–	$\mu s$

### Hard Standby and Hard Reset

The hard standby state is reached by the assertion of the XSHUTDOWN pad (hard reset). Register values are not retained by this action, and will be returned to their default values once hard reset is completed. The minimum power consumption is achieved by the hard standby state. The details of the sequence are described below and shown in Figure 6.

1. Disable streaming if output is active by setting mode\_select 0x301A[2] = 0.
2. The soft standby state is reached after the current row or frame, depending on configuration, has ended.
3. Assert XSHUTDOWN (active LOW) to reset the sensor.
4. The sensor remains in hard standby state if XSHUTDOWN remains in the logic “0” state.



Figure 6: Hard Standby and Hard Reset

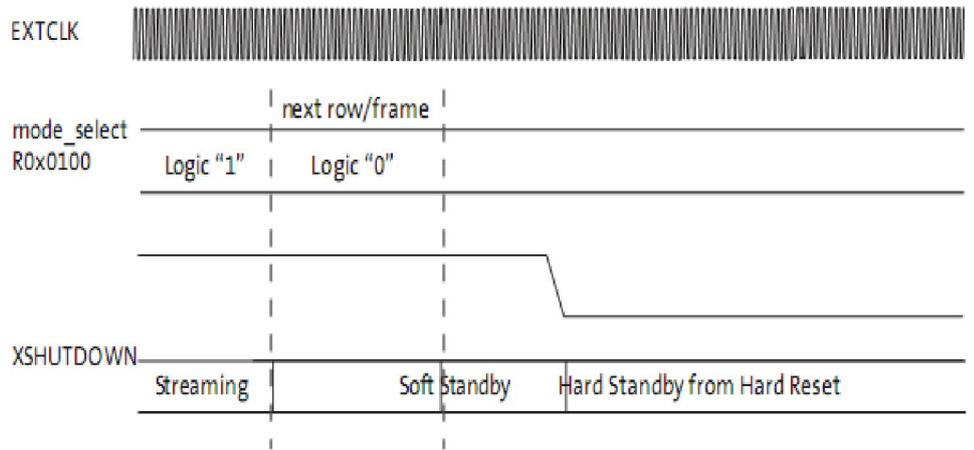
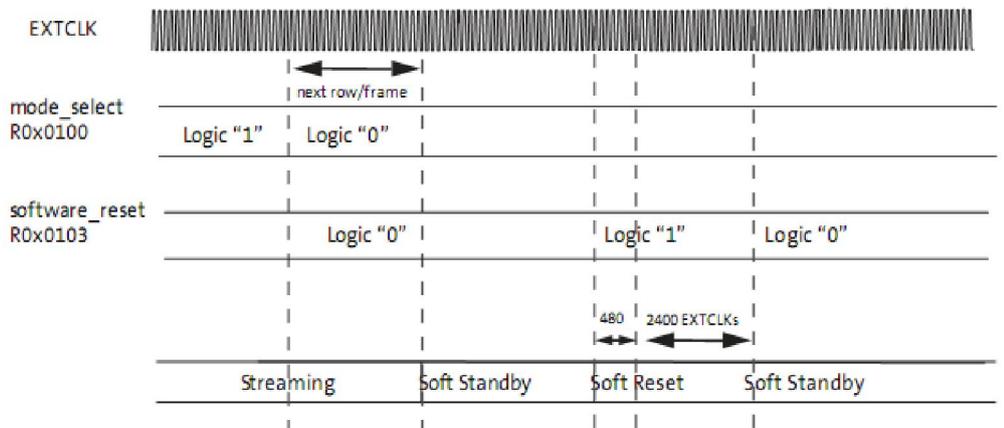


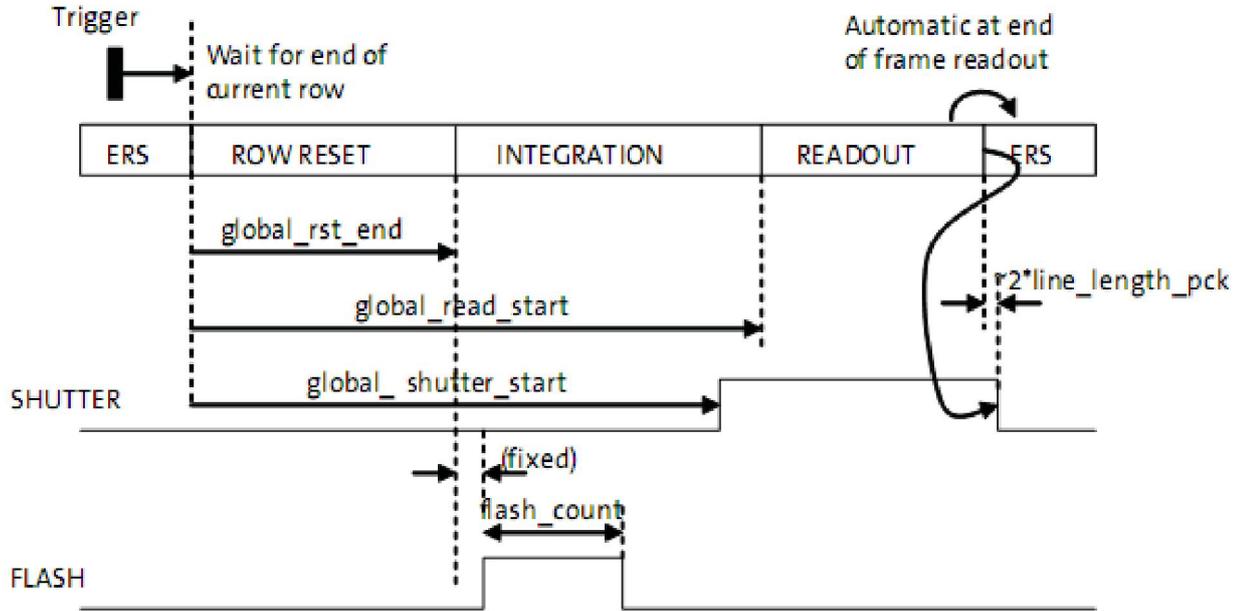
Figure 7: Soft Standby and Soft Reset



BYL



Using FLASH with Global Reset



BYD Config



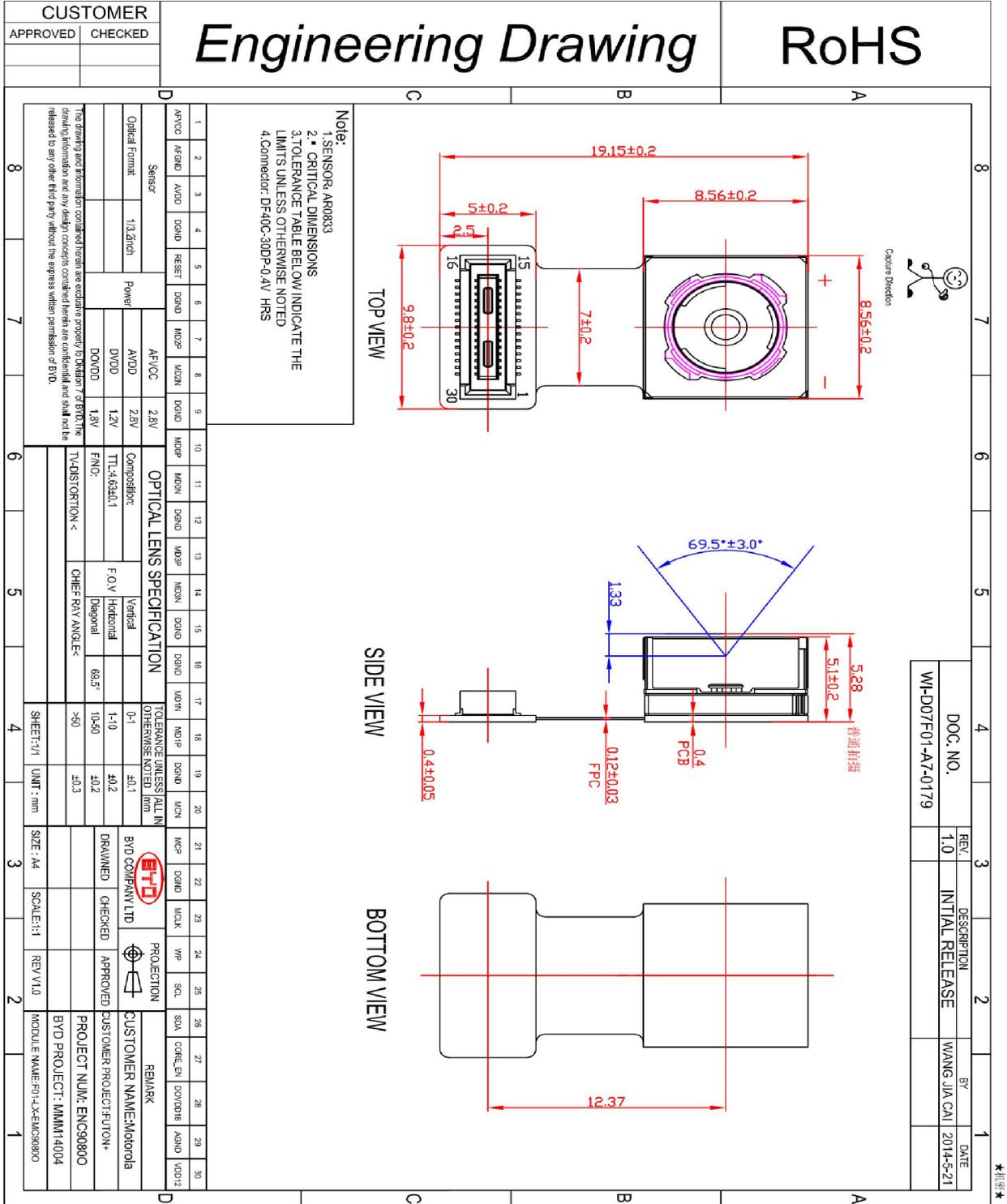
## Testing

Table6. Reliability testing

No	Test Item	Test Conditions	Judge standard
1	Temperature Change shock test	High Temp. : $80 \pm 3^{\circ}\text{C}$ Low Temp. : $-30 \pm 3^{\circ}\text{C}$ Temp. changeover time : 30min Test duration : 24 cycles	No image distort and good color rendition.
2	High Temp & Damp test	Temp. : $60^{\circ}\text{C} \pm 2^{\circ}\text{C}$ Damp : $90\% \pm 3\%\text{RH}$ Test duration : 48h	No image distort and good color rendition. Not to be dewy
3	Low Temperature Storage	Temp. : $-30^{\circ}\text{C} \pm 3^{\circ}\text{C}$ Test duration : 48h	No image distort and good color rendition.
4	High Temperature Storage	Temp. : $80 \pm 3^{\circ}\text{C}$ Test duration : 48h	No image distort and good color rendition.
5	ESD(Electrostatic Discharge)	Voltage : 10kv time : 3	No image distort and good color rendition.
6	Vibration (Package State)	Frequency range : 5-200HZ amplitude : 0.75mm Duration 3 h for each position. Test all 3 axes (X, Y, Z)	No image distort ,good color rendition , no white, black, colorful dot.
7	Drop test Free fall (Package State)	Surface (floor) : Concrete or steel Number of drops : 6 face*2 Positions : Random Height : 150cm	No image distort ,good color rendition , no white, black, colorful dot.



# Appendix1: Drawing

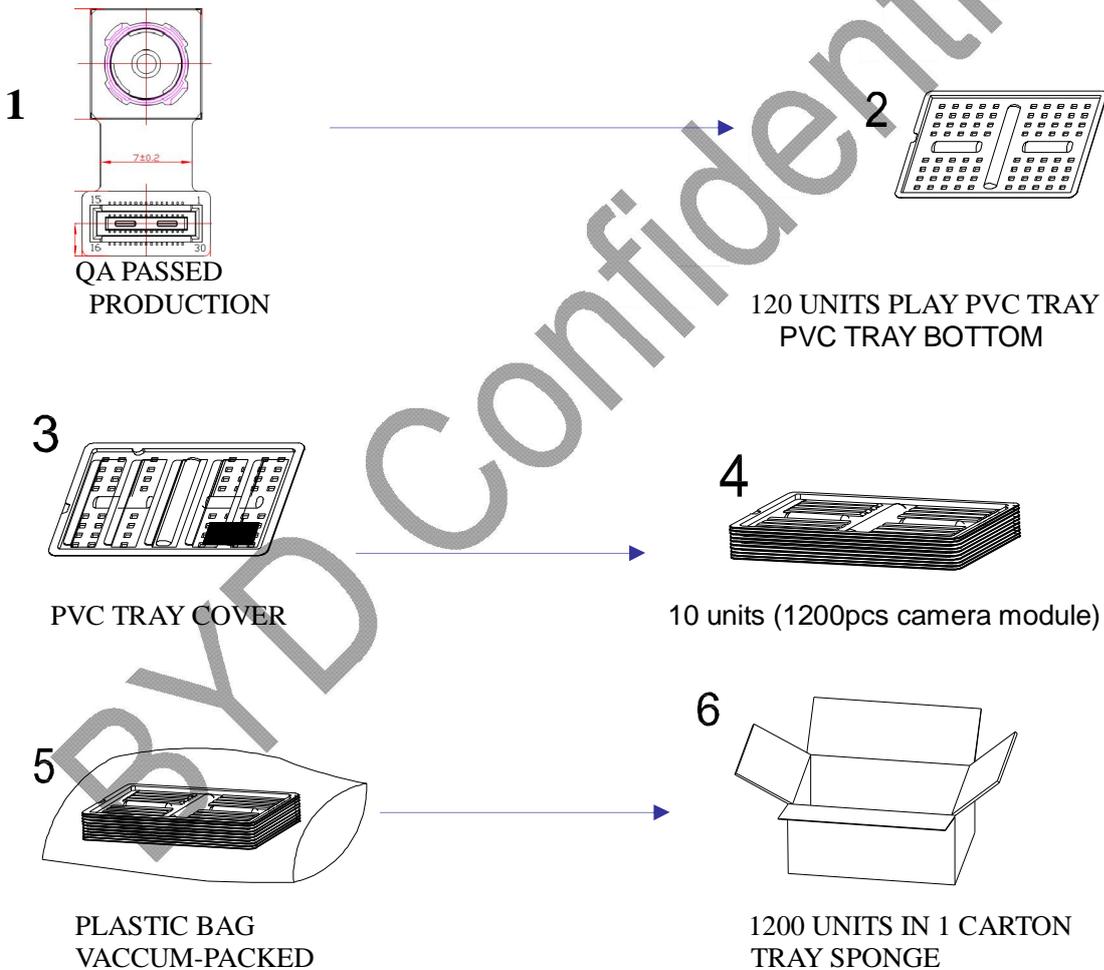


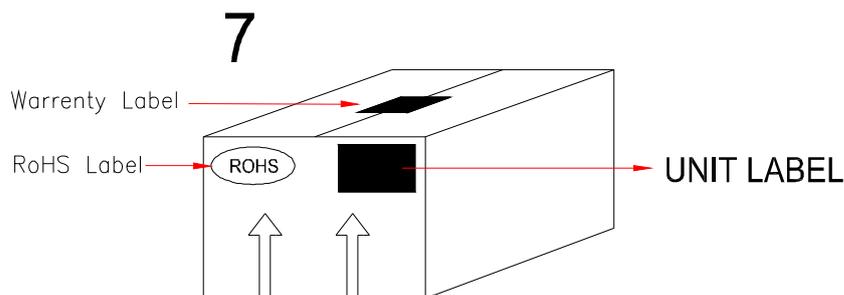


## Appendix 1: Packaging

The package must prevent damage to the components during transport and must be suitable for electrostatic-sensitive devices. The single camera modules shall be delivered in a reusable tray of antistatic plastic material. Several cameras shall be packed in one tray. The tray has separate holders for each camera-module.

Example:





Warranty label, ROHS label,和 UNIT label.

**TRAY SPECIFICATION:**

Material: black antistatic PS

Resistance: <1010

Dimension:260 (W) x 180 (D) x 11 (H) mm (Top tray and bottom tray assembly)

Capacity: 120 units (120pcs camera module)

**ESD SHIELDING BAG SPECIFICATION:**

Resistance: 107~1010

Dimension:430 (W) x 380 (D) x 0.075 (T) mm

Capacity : 10 units (1200pcs camera module)

**CARTON SPECIFICAITON:**

Dimension:276 (W) x 198 (D) x 113 (H) mm

**PAPER SHEET SPECIFICAITON:**

Capacity : 1 units (1200pcs camera module)

Dimension:270 (W) x 192 (D) x 2.5 (T) mm